REMARKS

Upon entry of the Amendment, Claims 1-21 will be pending in the application. Claim 21 is new. Support for Claim 21 is found in the specification such as on page 21, lines 4-5. Therefore, no new matter has been added.

I. Claim Rejection - 35 U.S.C. § 102

Claims 1-2, 12, and 20 have been rejected under 35 U.S.C. § 102(b) as allegedly being anticipated by U.S. Patent No. 4,845,310 to Postupak ("Postupak '310").

Applicants respectfully traverse.

Claim 1 recites exposing and developing a silver salt-containing layer provided on a support to form a metal silver portion and a light transmitting portion.

Additionally, Claim 20 recites exposing and developing a silver salt-containing layer provided on a support to form a metal silver portion in an exposed portion and the light-transmitting portion in an unexposed portion.

In contrast, Postupak '310 discloses that a continuous layer of photoresist is deposited over a conductive surface of a mandrel, exposed to actinic radiation through a photomask, developed, and the unexposed portions removed to yield a conductive pattern of the underlying conductive mandrel surface corresponding to the pattern of the photomask. *See*, col. 3, lines 46-51. More specifically, Example 1 of Postupak '310 discloses producing an electroformed nickel grid pattern on a mandrel in accordance with the following steps:

(1) an imaged photomask having a desired nonlinear grid pattern is prepared;

(2) the imaged photomask is placed in contact with the photoresist-coated mandrel surface

(3) the photomask/photoresist/mandrel stack is placed in an ultraviolet radiation exposure chamber to activate the photoresist, producing a negative image;

(4) after removing the photomask, the photoresist is developed to remove the exposed portion to yield a conductive pattern defined by the remaining nonconductive photoresist on the mandrel surface;

(5) the mandrel is immersed in an electroforming solution containing vertically oriented anodes and an electrical potential is applied between the anodes and the mandrel which functions as the cathode, resulting in metallic nickel forming in the pattern of the photoresist on the mandrel surface; and

(6) the photoresist is removed from the mandrel surface.

See, col. 5, line 62 to col. 6, line 48.

In this context, Postupak '310 discloses as follows:

> a photomask is prepared by coating a plate with a photographic emulsion comprising silver halide which is exposed to actinic radiation through a master Pattern in the shape of the grid to be electroformed. Exposed areas of the photographic emulsion form a latent image which is developed by immersion in developing solutions which convert the silver halide to colloidal silver.

See, col. 5, lines 12-19 (emphasis added). The support recited in Claim 1 is not the plate disclosed in Postupak '310. In fact, Postupak '310 discloses that a photoresist is deposited on the mandrel. As such, Postupak '310 fails to describe or suggest that a silver salt containing layer on

a support is subject to exposure and development to directly form the metal silver portion and the light-transmitting portion on the support.

Further, Claims 1 and 20 recite subjecting the metal silver portion to physical development and/or plating to form the conductive metal portion consisting of the metal silver portion carrying conductive metal particles.

Postupack '310 fails to describe or suggest that a metal silver portion is plated. As described above in step (4), Postupack '310 discloses that the photomask is removed prior to plating. There is no silver salt-containing layer at the plating step disclosed in Postupak '310.

Further, Postupak '310 discloses that metal is deposited on the conductive exposed mandrel surface in the pattern as defined by the nonconductive photoresist. *See*, col. 4, lines 57-59. As a result, Postupak discloses that plating is conducted on the exposed surface of the mandrel, rather than the metal silver portion.

Claims 2 and 12 depend from Claim 1. As such, Claims 2 and 12 are novel for at least the same reasons as Claim 1.

Further, Claim 21 recites that the support is a plastic film, a plastic plate or a glass plate. Postupak '310 discloses that a substrate with a conductive surface is used as an electroforming mandrel, preferably a sheet of nickel or stainless steel. *See*, col. 4, lines 12-14. Nickel and stainless steel are different from a plastic film, a plastic plate or a glass plate. Therefore, Postupak '310 fails to describe or suggest the method recited in new Claim 21.

II. Claim Rejections - 35 U.S.C. § 103

The Office Action contains the following six (6) rejections under 35 U.S.C. § 103:

> Claims 3, 6, and 8 have been rejected under 35 U.S.C. § 103 as allegedly being unpatentable over Postupack '310 in view of U.S. Patent No. 3,989,522 to Poot et al. ("Poot '522");
>
> Claims 4-5 and 7 have been rejected under 35 U.S.C. § 103 as allegedly being unpatentable over Postupack '310 in view of U.S. Patent No. 4,160,669 to Habu et al. ("Habu '669");
>
> Claim 9 has been rejected under 35 U.S.C. § 103 as allegedly being unpatentable over Postupack '310 in view of U.S. Patent No. 4,392,796 to Monroe ("Monroe '796");
>
> Claim 10 has been rejected under 35 U.S.C. § 103 as allegedly being unpatentable over Postupack '310 in view of U.S. Patent No. 5,288,313 to Portner ("Portner '313").
>
> Claim 11 has been rejected under 35 U.S.C. § 103 as allegedly being unpatentable over Postupack '310 in view of U.S. Patent No. 4,631,214 to Hasegawa ("Hasegawa '214").
>
> Claim 13 has been rejected under 35 U.S.C. § 103 as allegedly being unpatentable over Postupack '310 in view of U.S. Patent 6,787,204 to Chaussade et al. ("Chaussade '204") and U.S. Patent No. 4,831,491 to Mueller et al. ("Mueller '491").

Applicants respectfully traverse.

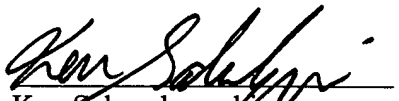
Each of the above rejections are grounded on Postupak '310. As described above, Postupak '310 is deficient in failing to teach or suggest exposing and developing a silver salt-containing layer provided on a support to form a metal silver portion and a light transmitting portion and subjecting the metal silver portion to physical development and/or plating to form the conductive metal portion consisting of the metal silver portion carrying conductive metal particles.

Poot '522, Habu '669, Monroe '796, Portner '313, Hasegawa '214, Chaussade '204, and Mueller '491 are relied upon for teachings unrelated to the above deficiencies in Postupak '310. In this regard, Poot '522, Habu '669, Monroe '796, Portner '313, Hasegawa '214, Chaussade '204, and Mueller '491 do not make up for the deficiencies in Postupak '310.

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



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